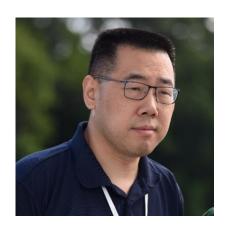# Biographies of IBM Research Presenters

Huiming Bu

Dr. Huiming Bu is Vice President of IBM Semiconductors Global R&D and Albany Operations at IBM Research.

Dr. Huiming Bu is responsible for global IBM Semiconductors R&D strategy across world-wide labs. He oversees R&D activities in advanced logic, chiplet and advanced packaging, emerging memory, and analog AI hardware at IBM Research.

In addition to driving semiconductor technology R&D agenda, Huiming is also responsible for IBM Research Albany site and fab operations.

Dr. Bu has 18+ years of professional experience in semiconductor technology R&D at IBM after he received his Ph.D. in Electrical Engineering from Yale University. Huiming has authored/co-authored 100+ technical publications and holds 100+ patents in semiconductor area.

Dr. Huiming Bu started his technical career at IBM on High-κ/Metal Gate project and then led SOI FinFET research for IBM's 14nm node technology. After that, Dr. Bu and his team delivered 10nm/7nm technology. They are now working on 2nm development and 1nm & beyond pathfinding R&D for IBM and its Joint Development Alliance (JDA) partners.